

L Number	Hits	Search Text	DB	Time stamp
1	1016979	fiber\$1 or fibre\$1 or waveguide\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:11
2	251326	optic\$3 near5 (fiber\$1 or fibre\$1 or waveguide\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:11
3	27336	(optic\$3 near5 (fiber\$1 or fibre\$1 or waveguide\$1)) and integrated	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:12
5	89205	laser adj diode\$1 or photodiode\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:14
6	42499	(reflect\$4 or mirror) same (optic\$3 near5 (fiber\$1 or fibre\$1 or waveguide\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:15
7	6114	((optic\$3 near5 (fiber\$1 or fibre\$1 or waveguide\$1)) and integrated) and (laser adj diode\$1 or photodiode\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:17
8	2593	((reflect\$4 or mirror) same (optic\$3 near5 (fiber\$1 or fibre\$1 or waveguide\$1))) and (((optic\$3 near5 (fiber\$1 or fibre\$1 or waveguide\$1)) and integrated) and (laser adj diode\$1 or photodiode\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:17
9	7291	(adhesive or resin or epoxy) and chip adj mount\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:19
10	1132	((semiconductor or CMOS) adj chip\$1) and (laser adj diode\$1 or photodiode\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:20
11	39	((reflect\$4 or mirror) same (optic\$3 near5 (fiber\$1 or fibre\$1 or waveguide\$1))) and (((optic\$3 near5 (fiber\$1 or fibre\$1 or waveguide\$1)) and integrated) and (laser adj diode\$1 or photodiode\$1))) and ((adhesive or resin or epoxy) and chip adj mount\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:21
12	7	((semiconductor or CMOS) adj chip\$1) and (laser adj diode\$1 or photodiode\$1)) and (((reflect\$4 or mirror) same (optic\$3 near5 (fiber\$1 or fibre\$1 or waveguide\$1))) and (((optic\$3 near5 (fiber\$1 or fibre\$1 or waveguide\$1)) and integrated) and (laser adj diode\$1 or photodiode\$1))) and ((adhesive or resin or epoxy) and chip adj mount\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/21 18:21